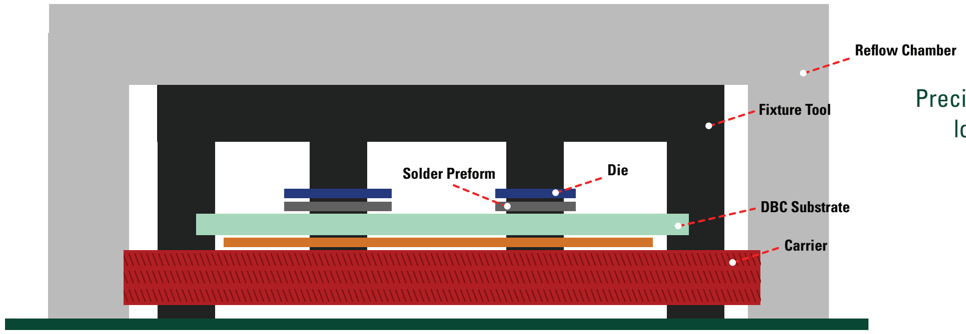
SOLUTIONS FOR POWER MODULE ASSEMBLY

THE CHALLENGE:

Power Module Assembly Tooling



Precise assembly alignment is required to ensure long-term reliability and consistent quality

Elaborate fixture tools are expensive to design/maintain, and add complexity to the reflow process

- P&P Preform
- P&P Die
- Close Fixing Tool
- Transport
- Close Soldering Tool
- Reflow Process
- Transport

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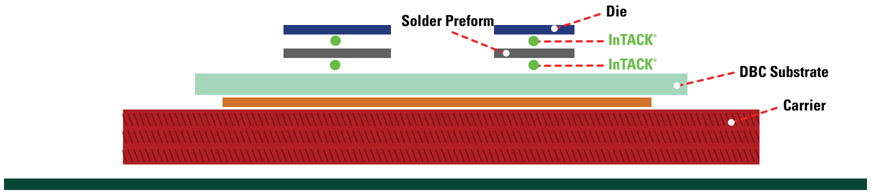
THE SOLUTION:

InTACK® Technology



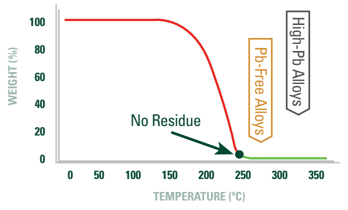
Tacking material maintains alignment during assembly and reflow

- ✓ No Tooling/ Fixturing Required
- ✓ Simplified Reflow Process
- ✓ Reduced Reflow Time
- ✓ Reduced Overall Process Time

- Dispense InTACK®
- P&P Preform
- P&P Die
- Transport
- Reflow Process
- Transport

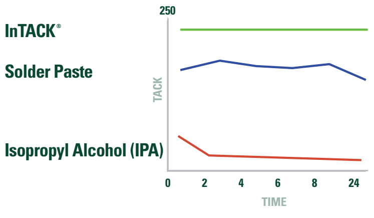
No Residue After Reflow

Ideal for no-flux soldering and sintering applications



Residue Analysis

Consistent High-Tack Strength Over Time



High-Tack and Long Working Time

Benefits:

- ✓ Maintain precise solder preform and assembly alignment
- ✓ Robust tacking and long working time
- ✓ Optimal performance in formic acid/vacuum reflow
- ✓ No impact to solder wetting, voiding
- ✓ No cleaning needed, no post-processing
- ✓ Dispensing application tested and process proven

InTACK® Technology is specifically designed to achieve high-quality solder performance, with no residue in flux-free reflow techniques commonly used in power module assembly.

Learn more: **www.indium.com**

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

Form No. 99999 R1

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